

# LN217RPH

## Square Type

□ 5.3 mm × 1.8 mm

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	70	mW
Forward current	$I_F$	25	mA
Pulse forward current *	$I_{FP}$	150	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +100	$^\circ\text{C}$

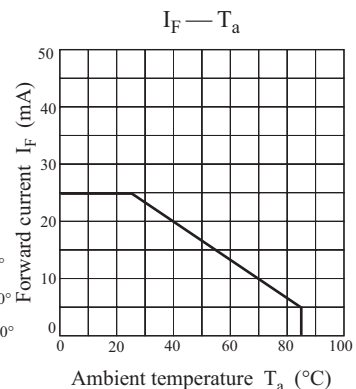
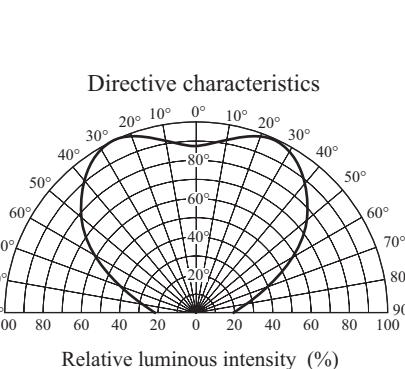
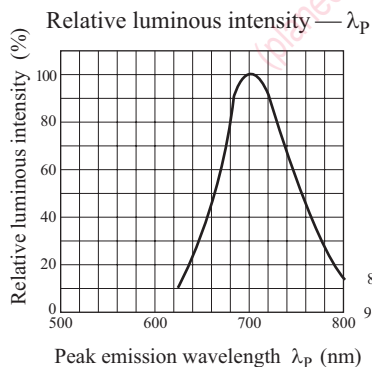
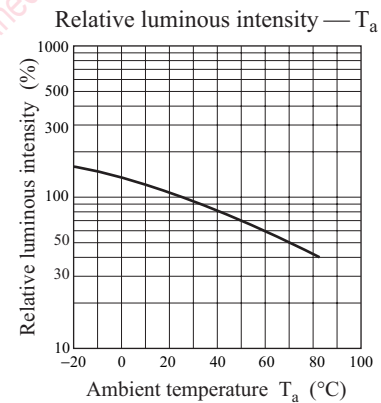
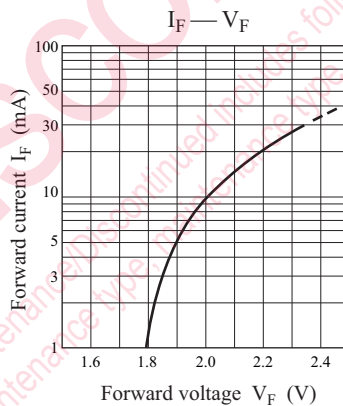
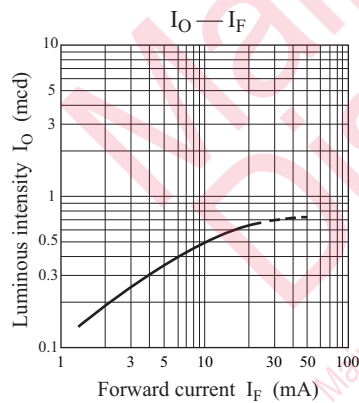
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Lighting Color

- Red

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		0.3	0.6		mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			5	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 20\text{ mA}$		2.2	2.8	V
Peak emission wavelength	$\lambda_p$	$I_F = 20\text{ mA}$		700		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		100		nm



2.0 Max. NOT SOLDERED

5.5 ± 0.2

5.3 ± 0.2

6.0

8.0 ± 0.2

2.0

0.8

0.6

0.5

4.85

5.35 ± 0.3

1.5

28.0 ± 1.0

2 - 0.8 Max

2 - 0.6 ± 0.1

2.54

1

2

1.5

4.0 ± 0.2

2.0 ± 0.2

1.8 ± 0.2

0.6 ± 0.1

- Pin name  
1: Anode  
2: Cathode

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